



'NITRALLOY'

NITRALLOY is an alloy for flow soldering printed circuits to the highest standard, produced from very high quality metals which are smelted under a nitrogen atmosphere. This process minimises the formation of superficial oxides during manufacture. When used, **NITRALLOY** stays bright and faults such as bridges, flags and spikes are reduced to an absolute minimum. Maximum advantage can be gained from **NITRALLOY** bar solder when used with flow solder machines having a "nitrogen blanket" facility although increased performance will be gained in conventional "open atmosphere" types. This alloy exceeds the requirements laid down in the Standards: NFC 90550, DIN 1707 and B.S.219 code AP, BS EN Alloy No.1a.

Chemical Characteristics

Amount of Tin:	62.4% to 63.6 %
Amount of Lead:	Remainder
Tin and lead from first melting purity:	>99.95%.

Chart of maximum impurities, example:

Cu	Ag	Cd	Sb	Bi
<0.05%	<0.005%	<0.005%	<0.05%	<0.01%

Fe	Zn	Al	As	S
<0.02%	<0.001%	<0.001%	<0.01%	<0.001%

Cl	P	Others
<0.001%	<0.001%	<0.05%

Physical Characteristics, standard:

*ALLOY 60/40	
Melting point	Solidus to Liquidus @ 183°C Eutectic.
Specific weight	8.4
Working temperature	230 to 260°C. Optimum @ 235 °C

Supplied as:

Bars	Extruded ~ 900g Bars in cartons of 24. (Exact Tare weight stated on carton).
Sticks	~250g in Cartons of 25 Kgs.
Granules	Containers of 20 Kgs.
Ingots	Approximate weight 3.9 Kgs
Wire	On spools of 15 Kgs - 20 Kgs.

Storage:

Original packaging at a temperature of 20°C for 12 months.